



NEWS RELEASE

MALAYSIA AND SINGAPORE COMPANIES SIGN JOINT VENTURE AND TECHNOLOGY LICENSE AGREEMENT FOR LATEST WAFER BUMPING AND FLIP CHIP TECHNOLOGY

Singapore, 22 September 2004 – Unisem (M) Berhad (“Unisem”) and Advanpack Solutions Pte Ltd (“APS”) today enters into an a joint-venture agreement (“JV Agreement”) to establish a joint venture company that will be the recipient of the latest wafer bumping and flip chip technology and will be engaged in the bumping and packaging of semiconductor devices using APS’ proprietary technologies. (“Joint-Venture”)

On 22 September 2004, simultaneously with the execution of the JV Agreement, Unisem Technologies Sdn Bhd (“UTSB”), a wholly-owned subsidiary of Unisem, entered into a technology license agreement with APS (“License Agreement”) for UTSB to license from APS its wafer bumping and advanced packaging technologies as well as the right to manufacture and sell the products.

Pursuant to the JV Agreement, upon the fulfilment of the conditions precedent, the issued and paid-up share capital of UTSB shall be increased to USD15 million. Unisem will contribute cash for 65% of the initial investment while APS will contribute license, technology transfer fee and royalties for a 35% stake in the Joint Venture.

Mr John Chia, the Chairman/Managing Director of Unisem commented: “Through the Joint Venture and Licensing Agreement, the Unisem Group will be able to acquire the industry-leading technology for wafer bumping and wafer level chip scale packaging technologies. APS’ technologies in wafer bumping and advanced packaging capabilities will allow Unisem to position itself in the high growth markets for flip chip and wafer level packaging.

Mr. Jimmy Chew Hwee Seng, the CEO of APS added: “The partnership of our technologies and Unisem’s high volume and low cost manufacturing capabilities bodes well for the advancement of this Joint Venture in the semiconductor industry.”

About Unisem (M) Berhad (www.unisem.com.my)

Unisem (M) Berhad, a leading semiconductor packaging and test services company in Malaysia, has its main packaging and test facilities in Ipoh, Malaysia with additional packaging and testing facilities in Wales, United Kingdom. Unisem offers an integrated suite of packaging and test

services for semiconductor companies such as wafer probe, a wide range of leadframe and substrate IC packaging, high-end RF and mix-signal test, tape & reel and drop-shipment services.

About Advanpack Solutions Pte. Ltd. (www.advanpack.com)

APS is an associated company of Advanced System Automation Ltd (“ASA”), a listed company on the SGX-SESDAQ. APS develops proprietary technology and provides innovative and integrated flip chip solutions to companies that manufacture semiconductors.

Media Contact:

Unisem (M) Berhad

Ruth Chin

Email: ruthchin@unisem.com.my

Advanpack Solutions Pte. Ltd.

Ch'ng Han Shen

Email: hschng@advanpack.com